

# Kemet

## DUAL FACE GRINDING ,LAPPING & POLISHING MACHINE

Kemet Dual Face Machines grind, lap & polish both flat faces of the components at the same time.

Able to process a wide range of materials and achieve very tight tolerance and consistently

- 5 carriers are driven for smooth action when grinding or lapping fragile parts
- Plate and carrier speeds variable through AC frequency inverters.
- Custom Fine Grinding, Grinding or Lapping plates are available for optimum operation.

### Options

- Automatic Thickness Control
- Load Cell Pressure Control
- HMI Touch Panel Control



Specification	DS 16	DS 18	DS 20
Diameter Of Lapping Plate	Dia. 1155 x ID 360 mm	Dia. 1262 x ID 535 mm	Dia. 1355 x ID 485 mm
Maximum Diameter Of Products	Dia. 390 mm	Dia. 390 mm	Dia. 450 mm
Diameter Of Carrier (PCD)	Dia. 423.33 (PCD) mm	Dia. 423.33 (PCD) mm	Dia. 423.33 (PCD) mm
Number Of Carrier	5 Pcs	6 Pcs	6 Pcs
Minimum Thickness Of Products	0.3 mm	0.3 mm	0.3 mm
Rotating Speed of Lower Lapping Plate (RPM)	0 ~ 60 RPM	0 ~ 60 RPM	0 ~ 60 RPM
Reversal Mechanism Of Carrier	CW & CCW	CW & CCW	CW & CCW
Machine Dimension [mm]	2020(W) x 1500(L) x 2260(H)	2530(W) x 1900(L) x 2260(H)	2730(W) x 2100(L) x 2260(H)
Estimated Weight	6500 kgs	7000 kgs	7500 kgs
Electric Supply	380V / 415V 3Ph 50Hz	380V / 415V 3Ph 50Hz	380V / 415V 3Ph 50Hz

NOTE : In the interests of development we reserve the right to change specification without notice.  
Dec 2024